Form PTO-1449 (SNL-Modified) (2-91) List of Patents and Publications for Applicant's Information Disclosure Statement

(use several sheets if necessary)

Atty Docket No: SD-7122/S-98,720 Serial Number:

APPLICANT: Kenneth A. Peterson, et al

GROUP:

FILING DATE: 2/25/02

## REFERENCE DESIGNATION

Ex'r Init		  Document	U.: No. Date	S. Patent Documents   Name   C	Sub Class Class	   File Date		10/08/2.	
4	[AA	[6,335,224	6/1/02	Protection of Microelectr		438/114	5/16/00	<del>1</del>	
	JAB	15,600,541	2/4/97	Vertical IC Chip Stack		361/707	8/3/95		
	AC	5,729,038	3/17/98	Silicon-Glass Bonded Wa	fers	257/460	12/15/95		
	AD	5,357,056	10/18/94	Chip Carrier For Optical	Device	174/524	3/23/93		
	AE	15,864,381	1/26/99	Automated Pupil Remapp	ing	351/205	7/10/96		
	AF	5,493,391	2/20/96	One Dimensional Wavefro	ont	356/121	7/11/94		
1	AG	5,352,852	10/4/94	Charge Coupled Device P	ackage	174/52.4	8/3/93		
LT	AH	4,742,182	5/3/88	Flatpack for Hermetic		174/52	11/6/86		

	OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)					
LT  BA	Kenneth A. Peterson, et al; "Pre-Release Plastic Packaging of MEMS and IMEMS Devices" Patent Application 09/572,720 filed 5/16/00.					
LT IBB	Kenneth A. Peterson, et al, "Microelectronic Device Package with an Integral Window"; Serial No. 09/571,335; filed 5/16/00; Notice of Allowance 2/6/01.					
LT  BC	[M.L. Minges, et al., "Electronic Materials Handbook, Vol. 1, PACKAGING", ASM International, Materials Park, OH, Jan., 1989, pp. 461-469.					
Yaminer:						

Examiner:

Lum Thai

Date Considered:

2/5/03